

ENGIS[®] MICROTECH VERTICAL GRINDING SYSTEM

This unique system is designed to grind Advanced Materials, including wafer backside grinding operations, achieving a high degree of flatness while optimizing surface finishes.

The Model HVG-250-AV Vertical Grinding Machine is designed for use with Engis diamond wheels which reduce processing times and overall costs.



ADVANCED MATERIALS PRODUCTS

FOR ADDITIONAL INFORMATION CONTACT THE ENGIS MICROTECH TEAM AT

WWW.ENGISCA.COM



MACHINE SPECIFICATIONS

MODEL	HVG - 250 - AV
WHEEL SPEED	1 ~ 2,000 RPM VARIABLE
WORK SPEED	1 ~ 2,000 RPM VARIABLE
MAX WORK SIZE	MAX Ø250MM
FEED RATE	0.01 ~ 10MM/MIN
RESOLUTION	0.004MM
ACCURACY	± 1UM
REPEATABILITY	±1 UM
WHEEL SIZE	MAX Ø250MM CUP TYPE
DIMENSIONS	1,100MM (W) X 950MM (D) X 1,970MM (H)
WEIGHT	1,450KG NET
POWER	220-240V, 3-PHASE, 50/60HZ
AIRLINE	6KGF/CM ² (CLEAN & DRY, VACUUM EJECTOR)

OPTIONS

- CHILLER FOR COOLANT TANK
 - MAGNETIC CHUCK
 - AUTO DRESSING SYSTEM
 - CERAMIC WORKHOLDERS
- DIAMOND GRINDING WHEEL Ø250MM

*ENGIS IS ABLE TO DELIVER A COMPLETE SYSTEM TO FIT EACH CUSTOMER'S UNIQUE REQUIREMENTS
AND OPTIMIZE THE MOST DEMANDING APPLICATIONS*

- HYPREZ COMPOSITE LAP PLATES
- DIAMOND AND COLLOIDAL LAPPING & POLISHING SLURRIES
- LUBRICANTS & CLEANERS
- POLISHING PADS/CLOTHS
- WAFER MOUNTING EQUIPMENT
- CONDITIONING RINGS

VGS250-002-0612



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